

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	− 0.5 to + 7.0	V
V <sub>I</sub>	DC Input Voltage	− 0.5 to + 7.0	V
V <sub>O</sub>	DC Output Voltage	− 0.5 to + 7.0	V
I <sub>IK</sub>	DC Input Diode Current V <sub>I</sub> < GND	− 50	mA
I <sub>OK</sub>	DC Output Diode Current V <sub>O</sub> < GND	− 50	mA
I <sub>O</sub>	DC Output Sink Current	± 50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	± 100	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	± 100	mA
T <sub>STG</sub>	Storage Temperature Range	− 65 to + 150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T <sub>J</sub>	Junction Temperature under Bias	+ 150	°C
θ <sub>JA</sub>	Thermal Resistance (Note 1)	250	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	250	mW
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I <sub>Latch-Up</sub>	Latch-Up Performance Above V <sub>CC</sub> and Below GND at 85°C (Note 5)	± 500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA/JESD78.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating Data Retention Only	1.65 1.5	5.5 5.5	V
V <sub>I</sub>	Input Voltage (Note 6)	0	5.5	V
V <sub>O</sub>	Output Voltage (HIGH or LOW State)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Free-Air Temperature	− 40	+ 85	°C
Δt/ΔV	Input Transition Rise or Fall Rate V <sub>CC</sub> = 1.8 V ± 0.15 V V <sub>CC</sub> = 2.5 V ± 0.2 V V <sub>CC</sub> = 3.0 V ± 0.3 V V <sub>CC</sub> = 5.0 V ± 0.5 V	0 0 0 0	20 20 10 5	ns/V

6. Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

# DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V <sub>CC</sub> (V)	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40°C to +85°C		Unit
				Min	Typ	Max	Min	Max	
V <sub>IH</sub>	HIGH Level Input Voltage		1.65 to 1.95	0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>			0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>		V
V <sub>IL</sub>	LOW Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.3 V <sub>CC</sub>		0.3 V <sub>CC</sub>	V
V <sub>OH</sub>	HIGH Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub>	I <sub>OH</sub> = -100 μA	1.65	1.55	1.65		1.55		V
			2.3	2.2	2.3		2.2		
			3.0	2.9	3.0		2.9		
			4.5	4.4	4.5		4.4		
		I <sub>OH</sub> = -4 mA I <sub>OH</sub> = -8 mA I <sub>OH</sub> = -16 mA I <sub>OH</sub> = -24 mA I <sub>OH</sub> = -32 mA	1.65	1.29	1.52		1.20		
			2.3	1.9	2.15		1.9		
V <sub>OL</sub>	Low-Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub>	I <sub>OL</sub> = 100 μA	1.65		0	0.1			V
			2.3		0	0.1			
			3.0		0	0.1			
			4.5		0	0.1			
		I <sub>OH</sub> = 4 mA I <sub>OH</sub> = 8 mA I <sub>OH</sub> = 16 mA I <sub>OH</sub> = 24 mA I <sub>OH</sub> = 32 mA	1.65		0.08	0.24			
			2.3		0.1	0.3			
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	0 to 5.5			±0.1		±1.0	μA
I <sub>OFF</sub>	Power OFF Leakage Current	V <sub>IN</sub> or V <sub>OUT</sub> = 5.5 V	0.0			1.0		10	
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5			1.0		10	μA

# AC ELECTRICAL CHARACTERISTICS t<sub>R</sub> = t<sub>F</sub> = 3.0 ns

Symbol	Parameter	Condition	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			−40°C ≤ T <sub>A</sub> ≤ 85°C		Unit
				Min	Typ	Max	Min	Max	
t <sub>PLH</sub>	Propagation Delay (Figure 3 and 4)	R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	1.8 ± 0.15 2.5 ± 0.2	2.0 1.0	8.0 3.5	9.5 5.8	2.0 1.0	10.5 6.2	ns
t <sub>PHL</sub>		R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	3.3 ± 0.3	0.8	2.6	3.9	0.8	4.3	
		R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 50 pF		1.2	3.2	4.8	1.2	5.2	
		R <sub>L</sub> = 1 MΩ, C <sub>L</sub> = 15 pF	5.0 ± 0.5	0.5	1.9	3.1	0.5	3.3	
		R <sub>L</sub> = 500 Ω, C <sub>L</sub> = 50 pF		0.8	2.5	3.7	0.8	4.0	

# CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	2.5	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 7)	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	9	pF
		10 MHz, V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	11	

7. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no-load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

# NL27WZ32

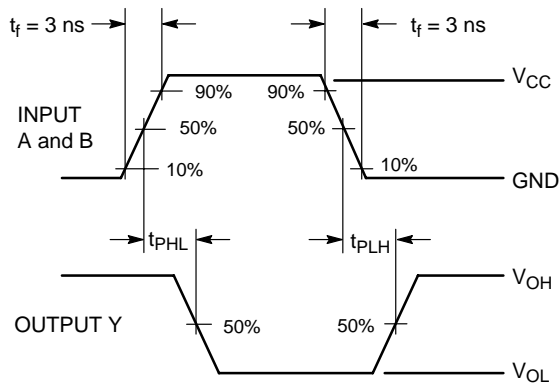
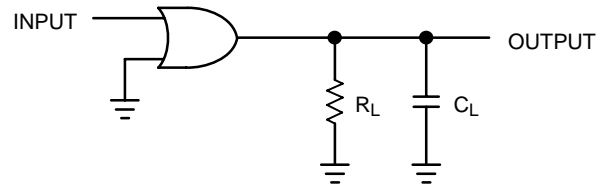


Figure 3. Switching Waveform



A 1-MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

## DEVICE ORDERING INFORMATION

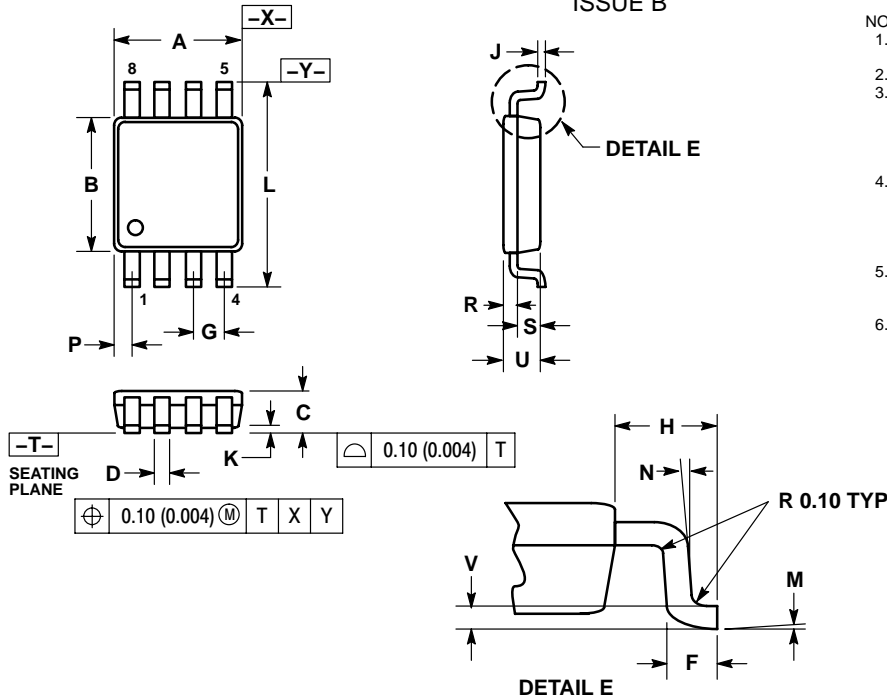
Device Order Number	Package Type	Tape and Reel Size <sup>†</sup>
NL27WZ32US	US8	178 mm, 3000 Units / Tape & Reel
NL27WZ32USG	US8 (Pb-Free)	178 mm, 3000 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NL27WZ32

## PACKAGE DIMENSIONS

US8  
US SUFFIX  
CASE 493-02  
ISSUE B

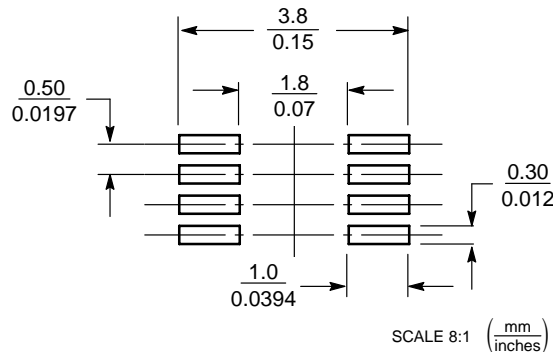


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION "A" DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD FLASH, PROTRUSION AND GATE BURR SHALL NOT EXCEED 0.140 MM (0.0055") PER SIDE.
4. DIMENSION "B" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTER-LEAD FLASH AND PROTRUSION SHALL NOT EXCEED 0.140 (0.0055") PER SIDE.
5. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203 MM. (300-800 °).
6. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.0508 (0.0002 °).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.90	2.10	0.075	0.083
B	2.20	2.40	0.087	0.094
C	0.60	0.90	0.024	0.035
D	0.17	0.25	0.007	0.010
F	0.20	0.35	0.008	0.014
G	0.50 BSC		0.020 BSC	
H	0.40 REF		0.016 REF	
J	0.10	0.18	0.004	0.007
K	0.00	0.10	0.000	0.004
L	3.00	3.20	0.118	0.126
M	0°	6°	0°	6°
N	5°	10°	5°	10°
P	0.23	0.34	0.010	0.013
R	0.23	0.33	0.009	0.013
S	0.37	0.47	0.015	0.019
U	0.60	0.80	0.024	0.031
V		0.12 BSC		0.005 BSC

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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